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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









4.0x4.0mm RIGHT ANGLE SURFACE MOUNT **LED LAMP**

Part Number: AA4040SECK

Super Bright Orange

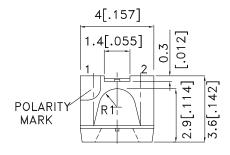
Features

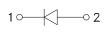
- •Single color.
- •Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- •Ideal for backlighting.
- ●Package: 500pcs / reel.
- •Moisture sensitivity level : level 4.
- ●RoHS compliant.

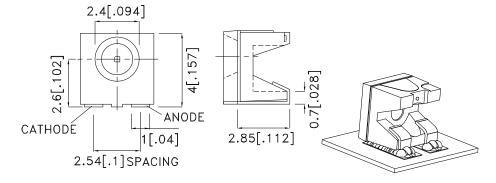
Description

The Super Bright Orange device is made with AlGaInP (on GaAs substrate) light emitting diode chip.

Package Dimensions







- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.4. The device has a single mounting surface. The device must be mounted according to the specifications.





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ERP: 1201004469

SPEC NO: DSAA8136 **REV NO: V.6** DATE: MAR/26/2009 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: X.J.Guo

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		2.	Min.	Тур.	201/2
AA4040SECK	Super Bright Orange (AlGaInP)	WATER CLEAR	70	300	90°

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

									
Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions			
λpeak	Peak Wavelength	Super Bright Orange	610		nm	IF=20mA			
λD [1]	Dominant Wavelength	Super Bright Orange	601		nm	IF=20mA			
Δλ1/2	Spectral Line Half-width	Super Bright Orange	29		nm	IF=20mA			
С	Capacitance	Super Bright Orange	15		pF	VF=0V;f=1MHz			
VF [2]	Forward Voltage	Super Bright Orange	2.1	2.5	V	IF=20mA			
lr	Reverse Current	Super Bright Orange		10	uA	V _R =5V			

- Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

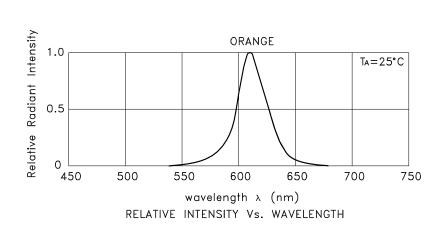
Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Orange		
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	195	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

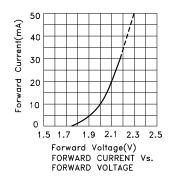
Note:

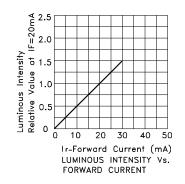
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

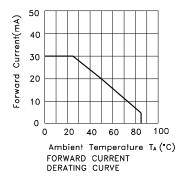
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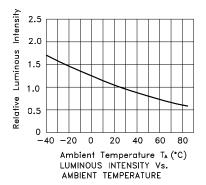


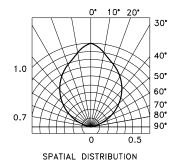
Super Bright Orange AA4040SECK











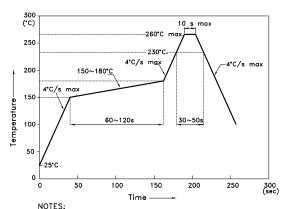
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AA4040SECK

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



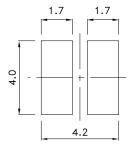
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

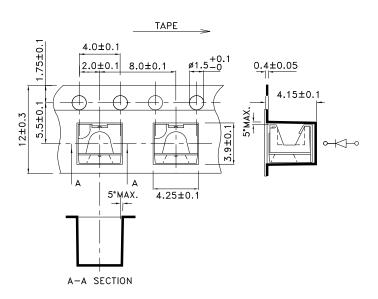
 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. to high temperature.

 3.Number of reflow process shall be 2 times or less.

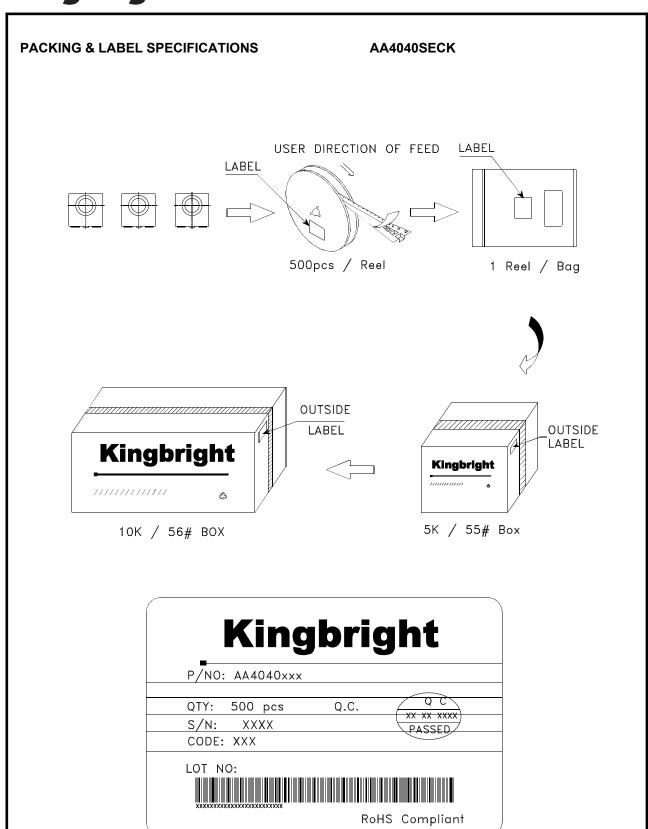
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Tape Dimensions (Units: mm)



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